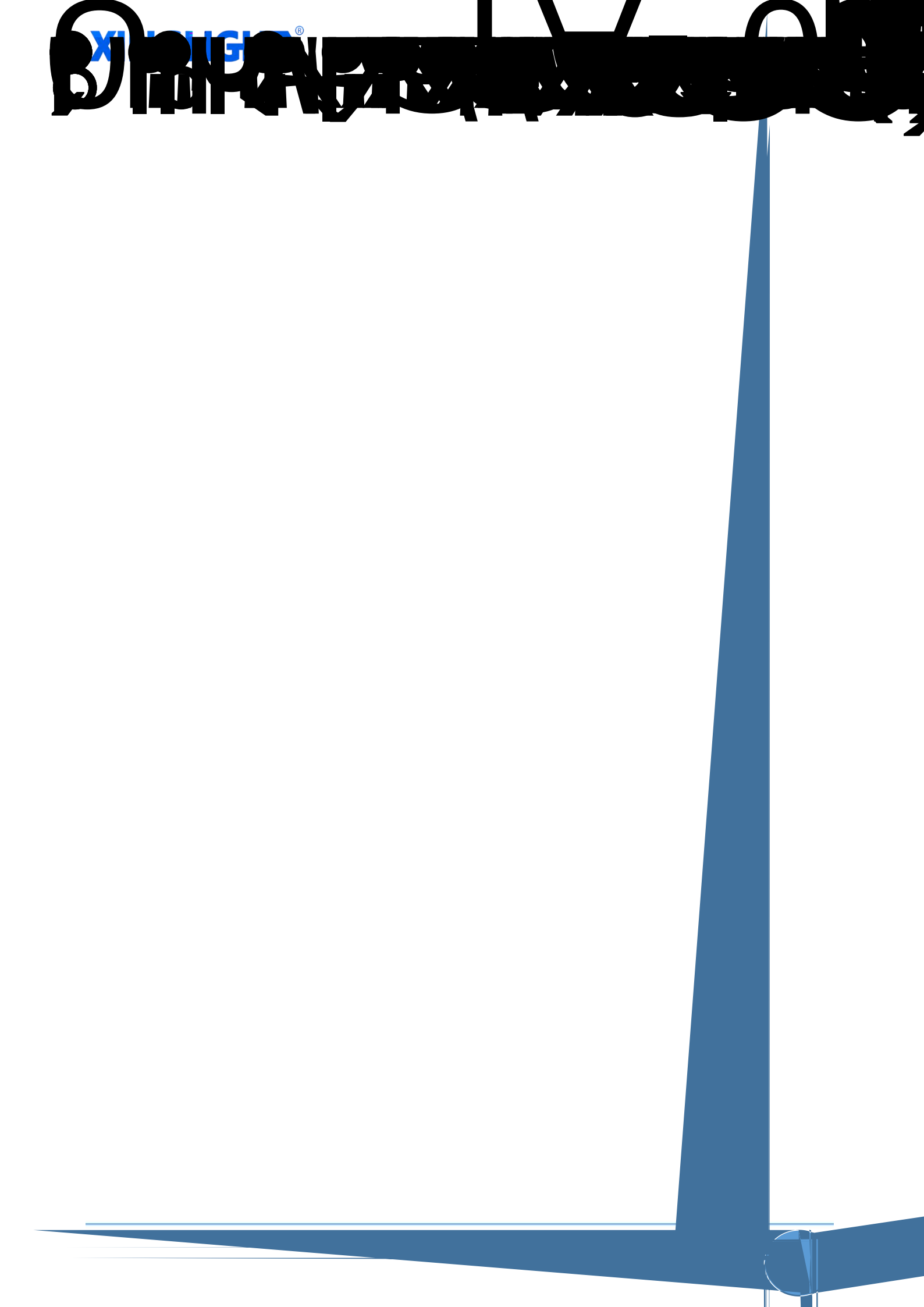
| | | | |
|---|---|---|---|
| Total Power Dissipation | $P_{TOT}$ | 200 | mW |
| Isolation Voltage *2 | $V_{ISO}$ | 3750 | Vrms |
| Rated Impulse Isolation Voltage | $V_{IOTM}$ | 5000 | V |
| Rated Repetitive Peak Isolation Voltage | $V_{IORM}$ | 600 | V |
| Thermal Resistance Junction-to-Air | $R_{\theta JA}$ | 430 | °C/W |
| Thermal Resistance Junction-to-Case | $R_{\theta JC}$ | 350 | °C/W |
| Thermal Resistance Junction-to-Lead | $R_{\theta JL}$ | 368 | °C/W |
| Operating Temperature | $T_{OPR}$ | -55 ~ +110 | °C |
| Storage Temperature Range | $T_{STG}$ | -55 ~ +125 | °C |
| Soldering Temperature *3 | $T_{SOL}$ | 260 | °C |

Notes

1. Pulse width≤1μs, Duty ratio: 0.001
2. 40 to 60% RH, AC for 1 minute
3. For 10 seconds